

#### **Features**

- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)
- HBM ESD protection level pass 8KV

**Note**: The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

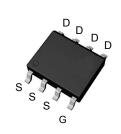
#### **Applications**

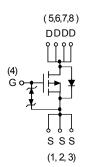
Power Management in LCD TV Inverter.

## **Product Summery**

-40V/-16.7A.

## **SOP-8 Pin Configuration**





## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit		
V <sub>DSS</sub>	Drain-Source Voltage	-40	V		
V <sub>GSS</sub>	Gate-Source Voltage	±25	V		
I <sub>D</sub> <sup>a</sup>	Continuous Drain Current (V <sub>GS</sub> =-10V)	T <sub>A</sub> =25°C	-16.7		
		T <sub>A</sub> =70°C	-13.3		
I <sub>DM</sub> a	Pulsed Drain Current (V <sub>GS</sub> =-10V)	OV) -66			
I <sub>S</sub> <sup>a</sup>	Diode Continuous Forward Current	-4	<b>⊢</b> Α		
ı b	Avalanche Current, Single pulse	L=0.1mH	-43		
I <sub>AS</sub> b		L=0.5mH	-24	7	
E <sub>AS</sub> b	Avalanche Energy, Single pulse	L=0.1mH	92	mJ	
		L=0.5mH	144		
Τ <sub>J</sub>	Maximum Junction Temperature		150	- °C	
T <sub>STG</sub>	Storage Temperature Range		-55 to 150		
$P_D^{a}$	Maximum Power Dissipation	T <sub>A</sub> =25°C	4.2	- w	
		T <sub>A</sub> =70°C	2.7		
$R_{\scriptscriptstyle{\thetaJA}}^{}a}$	Thermal Resistance-Junction to Ambient	t ≤ 10s	30		
		Steady State	75	°C/W	
R <sub>θJL</sub> <sup>c</sup>	Thermal Resistance-Junction to Lead	Steady State	24		

Note a : Surface Mounted on  $1in^2$  pad area,  $t \le 10$  sec.

Note b: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T<sub>j</sub>=25°C).

Note c: The power dissipation  $P_D$  is based on  $T_{J(MAX)}$  = 150°C, and it is useful for reducing junction-to-case thermal resistance ( $R_{\theta JC}$ ) when additional heat sink is used.



# **Electrical Characteristics** (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Static Ch	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-250μA	-40	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-32V, V <sub>GS</sub> =0V	-	-	-1	μА
		T <sub>J</sub> =85°C	-	-	-30	
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =-250μA	-1.5	-2	-2.5	<b>V</b>
$I_{GSS}$	Gate Leakage Current	$V_{GS}$ =±20V, $V_{DS}$ =0V	ı	-	±10	μΑ
R <sub>DS(ON)</sub> <sup>d</sup>	Drain-Source On-state Resistance	V <sub>GS</sub> =-20V, I <sub>DS</sub> =-16A	-	7	8.5	mΩ
		V <sub>GS</sub> =-10V, I <sub>DS</sub> =-16A	ı	7.9	10	
		V <sub>GS</sub> =-4.5V, I <sub>DS</sub> =-10A	-	11.5	16	
Diode Ch	naracteristics					
V <sub>SD</sub> <sup>d</sup>	Diode Forward Voltage	I <sub>SD</sub> =-1A, V <sub>GS</sub> =0V	-	-0.75	-1	V
t <sub>rr</sub>	Reverse Recovery Time	104 11 (11 1004)	-	26	-	ns
$Q_{rr}$	Reverse Recovery Charge	-I <sub>SD</sub> =-16A, dl <sub>SD</sub> /dt=100A/μs	-	19	-	nC
Dynamic	Characteristics <sup>e</sup>					
$R_{G}$	Gate Resistance	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,F=1MHz	-	3.2	-	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-20V, Frequency=1.0MHz	-	2764	-	pF
Coss	Output Capacitance		-	417	-	
$C_{rss}$	Reverse Transfer Capacitance		-	325	-	
t <sub>d(ON)</sub>	Turn-on Delay Time	$V_{DD}$ =-20V, $R_{L}$ =20 $\Omega$ , $I_{DS}$ =-1A, $V_{GEN}$ =-10V, $I_{CG}$ =6 $\Omega$	-	15	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	12	-	
t <sub>d(OFF)</sub>	Turn-off Delay Time		-	56	-	
t <sub>f</sub>	Turn-off Fall Time		-	21	-	
Gate Cha	arge Characteristics <sup>e</sup>					
$Q_g$	Total Gate Charge	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-10V, I <sub>DS</sub> =-16A	-	60	-	nC
$Q_{gs}$	Gate-Source Charge		-	7.6	-	
$Q_{gd}$	Gate-Drain Charge		-	15	-	

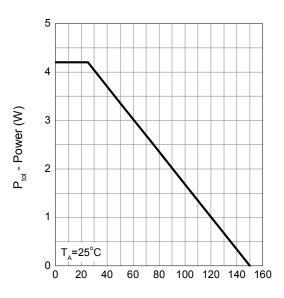
Note d : Pulse test; pulse width $\leq$ 300 $\mu$ s, duty cycle $\leq$ 2%.

Note e: Guaranteed by design, not subject to production testing.



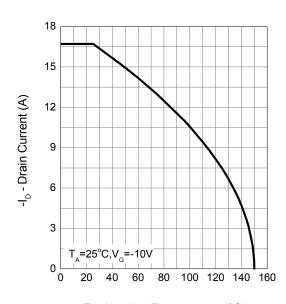
## **Typical Characteristics**

#### **Power Dissipation**



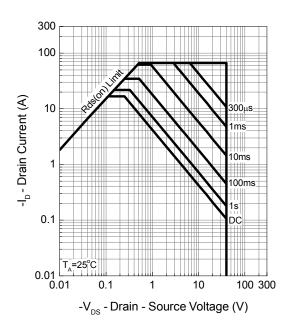
T<sub>i</sub> - Junction Temperature (°C)

#### **Drain Current**

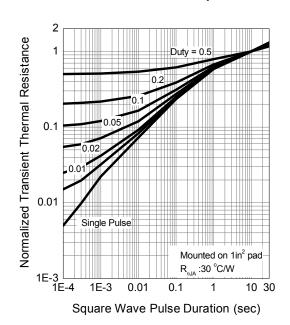


T<sub>i</sub> - Junction Temperature (°C)

### **Safe Operation Area**

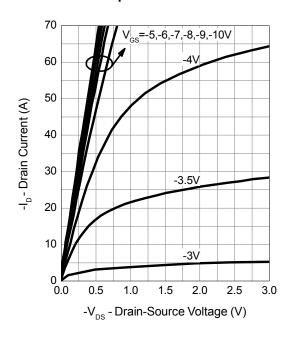


### **Thermal Transient Impedance**

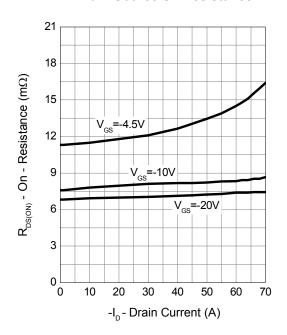




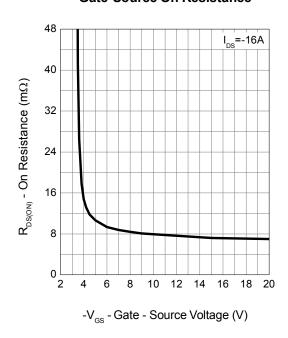
### **Output Characteristics**



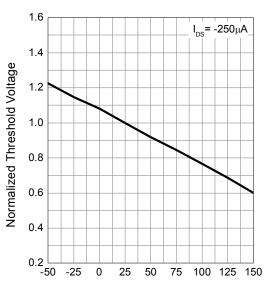
#### **Drain-Source On Resistance**



#### **Gate-Source On Resistance**



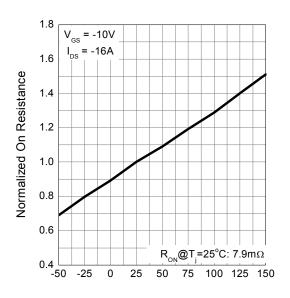
## **Gate Threshold Voltage**



T<sub>i</sub> - Junction Temperature (°C)

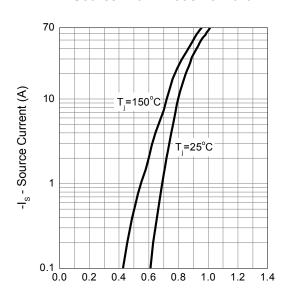


#### **Drain-Source On Resistance**



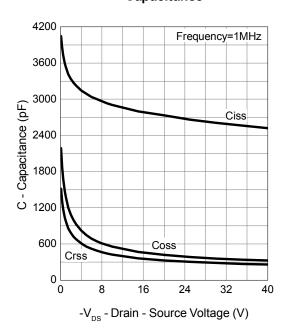
T<sub>i</sub> - Junction Temperature (°C)

## **Source-Drain Diode Forward**

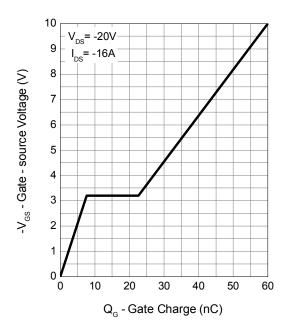


-V<sub>SD</sub> - Source - Drain Voltage (V)

#### Capacitance



### **Gate Charge**





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